EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	7175	((438/627) or (438/629) or (438/643) or (438/644) or (438/648) or (438/653) or (438/654) or (438/656) or (438/658) or (438/659) or (438/687)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/30 10:50
L2	29	1 and (implant$3 near10 seed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/30 10:50
S1	404806	("438"/$.ccls. or "257"/$.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/30 10:48
S2	1	("6770559").PN.	USPAT	OR	OFF	2005/11/28 12:52
S3	1	S2 and implant$3 same seed same (Zn or Sn or Cr or Ca or Ag or In)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 12:53
S4	1	S2 and (implant$3 same seed same (Zn or Sn or Cr or Ca or Ag or In))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:19
S5	1026	S1 and ((pattern$3 near5 (conduct$3 or metal)) same barrier) and (bond$3 same (wafer or substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:22
S6	11857	((electrolyt$2 or electroless) same barrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:22

EAST Search History

S7	424	S1 and ((pattern$3 near5 (conduct$3 or metal)) same barrier) and (bond$3 same barrier same (wafer or substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 14:47
S8	635	"1" and ((pattern$3 near5 (conduct$3 or metal or line)) same barrier) and (bond$3 same barrier same (wafer or substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 14:46
S9	404806	("438"/$.ccls. or "257"/$.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 14:47
S10	424	S9 and ((pattern$3 near5 (conduct$3 or metal)) same barrier) and (bond$3 same barrier same (wafer or substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 14:48
S11	66	S10 and (bond$3 same (first near3 (substrate or wafer)) and (second near3 (substrate or wafer)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 14:50
S12	404806	("438"/$.ccls. or "257"/$.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 18:01
S13	424	S12 and ((pattern$3 near5 (conduct$3 or metal)) same barrier) and (bond$3 same barrier same (wafer or substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 18:01
S14	66	S13 and (bond$3 same (first near3 (substrate or wafer)) and (second near3 (substrate or wafer)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 18:01

S15	48	S14 and (barrier near5 layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 18:01